

L Number	Hits	Search Text	DB	Time stamp
1	1669	((438/460) or (438/464) or (438/667) or (438/977)).CCLS.	USPAT; US-PGPUB	2004/10/14 13:09
2	233	((438/460) or (438/464) or (438/667) or (438/977)).CCLS.) and (thinning with (wafer or substrate))	USPAT; US-PGPUB	2004/10/14 13:09
3	32	((438/460) or (438/464) or (438/667) or (438/977)).CCLS.) and (thinning with (wafer or substrate))) and (warp warping)	USPAT; US-PGPUB	2004/10/14 13:11
4	129006	(wafer or substrate) with (thinning or thin or thinned)	USPAT; US-PGPUB	2004/10/14 13:11
5	4706	((wafer or substrate) with (thinning or thin or thinned)) and (warp or warping)\	USPAT; US-PGPUB	2004/10/14 13:11
6	4706	((wafer or substrate) with (thinning or thin or thinned)) and (warp or warping)	USPAT; US-PGPUB	2004/10/14 13:11
7	31	((wafer or substrate) with (thinning or thin or thinned)) and (warp or warping)) and (mmic)	USPAT; US-PGPUB	2004/10/14 13:13
8	120	(438/for.477).CCLS.	EPO; JPO; DERWENT; IBM_TDB	2004/10/14 13:14
9	114	(438/for.485).CCLS.	EPO; JPO; DERWENT; IBM_TDB	2004/10/14 13:13
10	0	((438/460) or (438/464) or (438/667) or (438/977)).CCLS.) and waffle	USPAT; US-PGPUB	2004/10/14 13:14
11	5	((438/460) or (438/464) or (438/667) or (438/977)).CCLS.) and waffle	USPAT; US-PGPUB	2004/10/14 13:14
12	271	((438/460) or (438/464) or (438/667) or (438/977)).CCLS.) and grid	USPAT; US-PGPUB	2004/10/14 13:15
13	30	((438/460) or (438/464) or (438/667) or (438/977)).CCLS.) and mmic	USPAT; US-PGPUB	2004/10/14 13:16
14	0	((438/for.477).CCLS.) and ((438/for.485).CCLS.)	EPO; JPO; DERWENT; IBM_TDB	2004/10/14 13:16
15	0	((438/for.477).CCLS.) and mmic	EPO; JPO; DERWENT; IBM_TDB	2004/10/14 13:17
16	0	((438/for.485).CCLS.) and mmic	EPO; JPO; DERWENT; IBM_TDB	2004/10/14 13:17
17	82	((438/for.477).CCLS.) and (thinning or thin)	EPO; JPO; DERWENT; IBM_TDB	2004/10/14 13:17